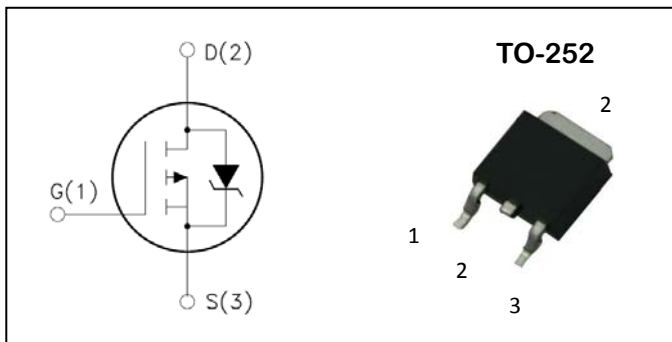


P-Channel Logic Level Enhancement Mode Field Effect Transistor**PRODUCT SUMMARY**

V_{DSS}	I_D	$R_{DS(ON)}$ (m Ω)
-60V	-15A	90m Ω

**Absolute Maximum Ratings** ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Ratings	Unit
Common Ratings				
V _{DSS}	Drain-Source Voltage		-60	V
V _{GSS}	Gate-Source Voltage		±20	
T _J	Maximum Junction Temperature		150	°C
T _{STG}	Storage Temperature Range		-55 to 150	°C
I _S	Diode Continuous Forward Current	TC=25°C	-15	A
Mounted on Large Heat Sink				
I _{DM}	300μs Pulse Drain Current Tested(1)	T _C =25°C	-50	A
I _D	Continuous Drain Current	T _C =25°C	-15	A
		T _C =100°C	-10	A
P _D	Maximum Power Dissipation	T _C =25°C	41	W
		T _C =100°C	16	W

Thermal Characteristics

Symbol	Parameter	Ratings	Unit
R_{thJC}	Thermal resistance junction-case max	3	$^\circ\text{C/W}$
R_{thJA}	Thermal resistance junction-ambient max	75	$^\circ\text{C/W}$

1. Pulse width limited by maximum junction temperature.

Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
On/off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250uA	-60	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -48V, V _{GS} =0V	--	--	1	uA
		V _{DS} =-40V,V _{GS} =0V T _J =125°C	--	--	10	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250uA	-1	-1.7	-3	V
I _{GSS}	Gate Leakage Current	V _{GS} = ± 20V, V _{DS} =0V	--	--	± 250	nA
R _{DS(ON)}	Drain-SourceOn-stateResistance(2)	V _{GS} = -10V, I _{DS} =-7A	--	42	55	mΩ
		V _{GS} = -4.5V, I _{DS} =-6A	--	100	135	
g _{FS}	Forward transconductance(2)	V _{DS} =- 10V, I _{DS} =-7A	--	9	--	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} =0V,	--	1130	--	pF
C _{oss}	Output Capacitance	V _{DS} = -25V,	--	122	--	
C _{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz	--	75	--	
Switching Characteristics						
t _{d(ON)}	Turn-on Delay Time(1)	V _{DS} =-20V,	--	7	--	ns
t _r	Turn-on Rise Time(1)	I _D = -1A, V _{GS} = -10V,	--	10	--	
t _{d(OFF)}	Turn-off Delay Time(1)	R _{GEN} =6 Ω	--	19	--	
t _f	Turn-off Fall Time(1)		--	12	--	
Q _g	Total Gate Charge(1)	V _{DS} =0.5V, V _{GS} = -10V,	--	12.5	--	nC
Q _{gs}	Gate-Source Charge(1)	I _{DS} =-7A	--	1.8	--	
Q _{gd}	Gate-Drain Charge(1)		--	3.7	--	
Diode Characteristics						
V _{SD}	Diode Forward Voltage(2)	I _{SD} = -7A, V _{GS} = 0	--	--	-1	V
t _{rr}	Reverse Recovery Time	I _{SD} =-7A, dI _{SD} /dt=100A/μs	--	37	--	ns
q _{rr}	Reverse Recovery Charge		--	53	--	nC

NOTES:

1. Independent of operating temperature.
2. Pulse Test : Pulse width ≤ 300 μ s, Duty cycle ≤ 2%

Typical Performance Characteristics

Figure 1: On-Region Characteristics

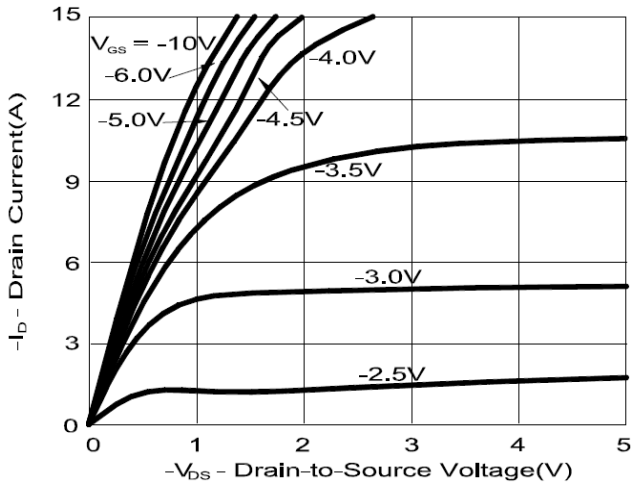


Figure 2: Transfer Characteristics

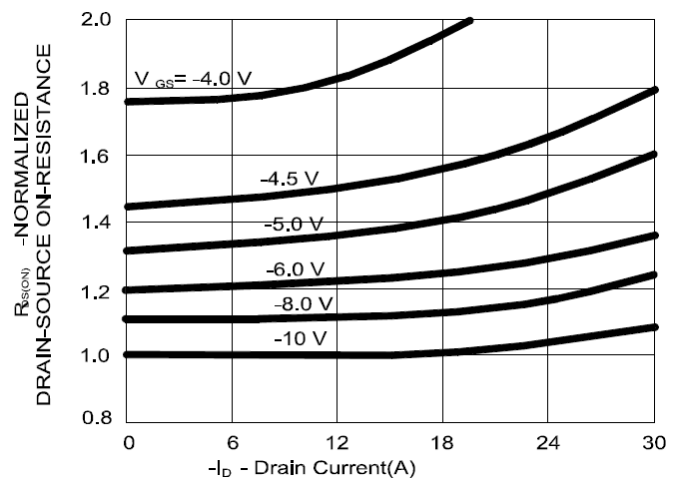


Figure 3: Transfer Characteristics

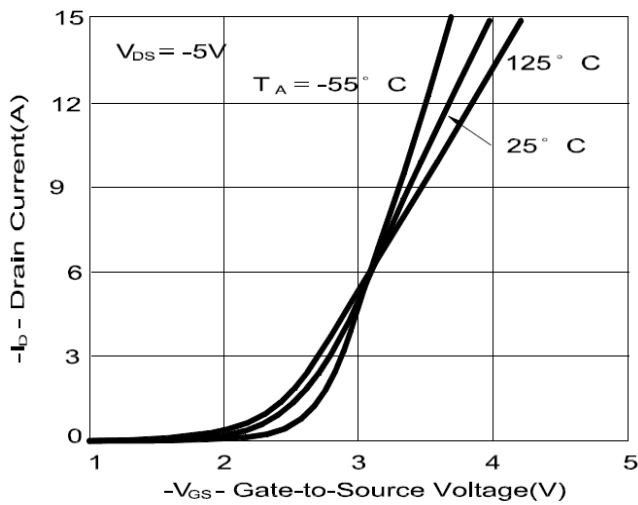


Figure 4: On-Resistance with Gate-to-source Voltage

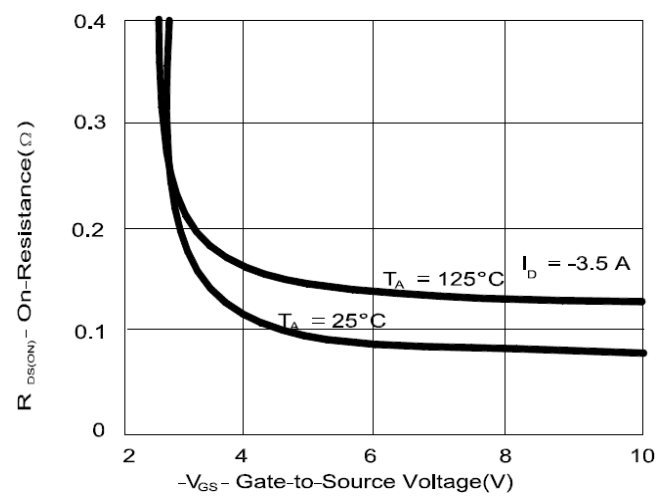


Figure 5: Capacitance Characteristics

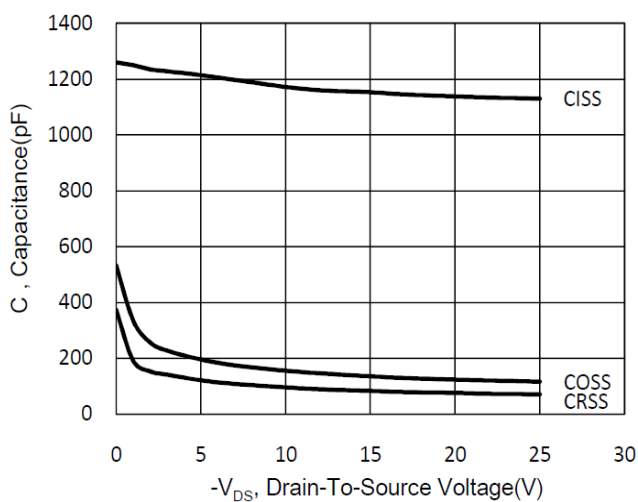


Figure 6: Gate Charge Characteristics

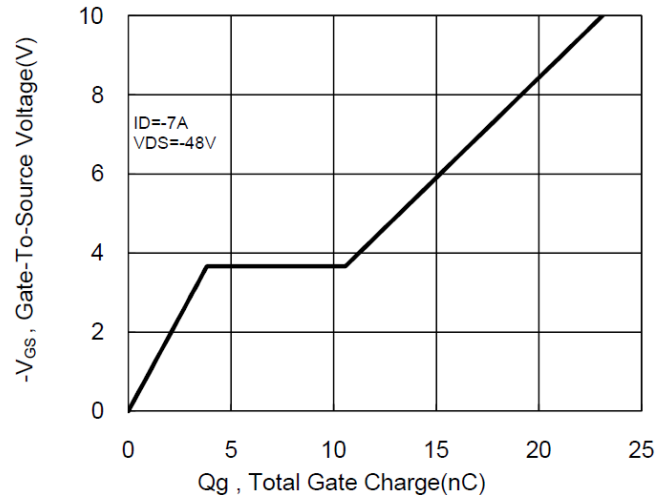


Figure 7: On-Resistance Variation vs. Temperature

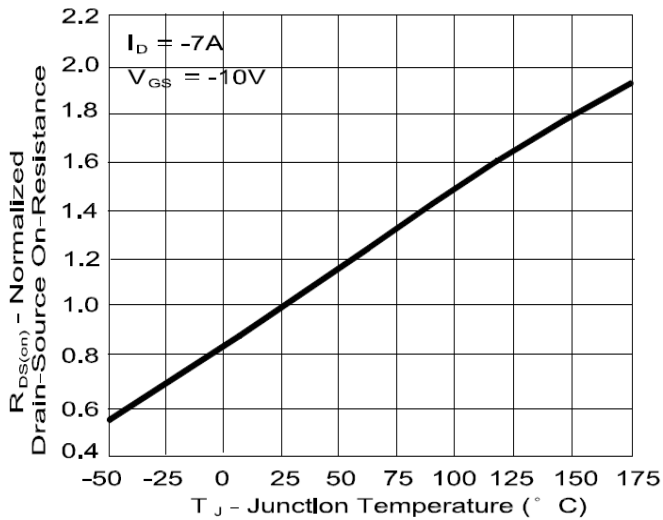


Figure 8: Body Diode Forward Voltage

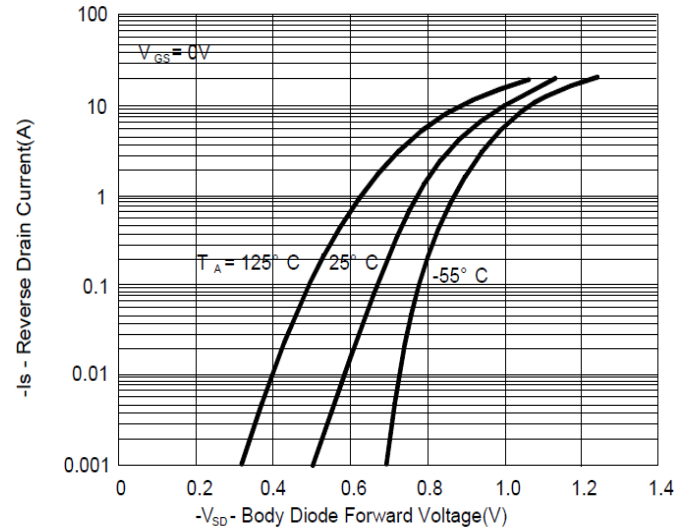


Figure 9: Maximum Safe Operating Area

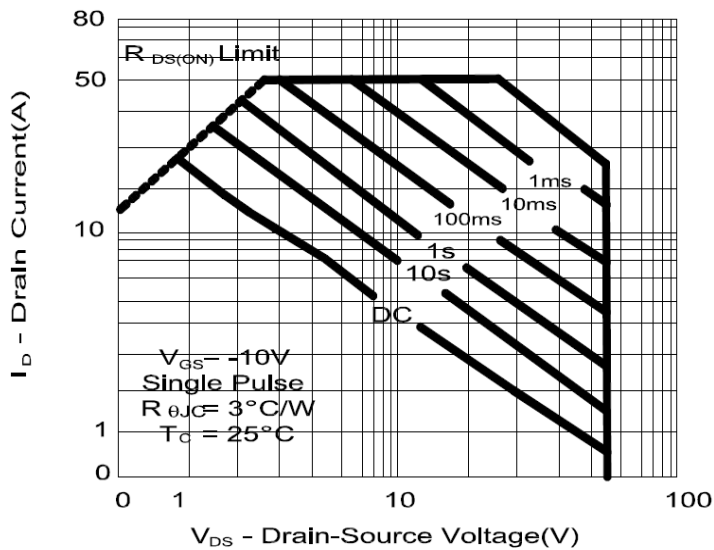


Figure 10: Pulse Maximum Power Dissipation

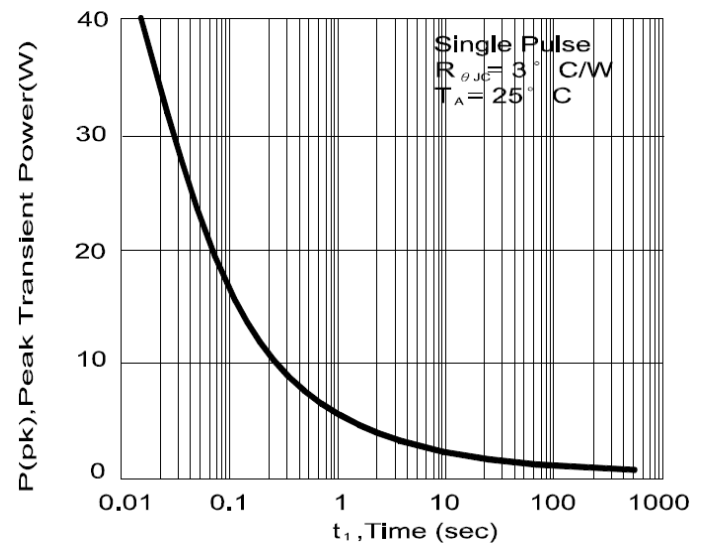
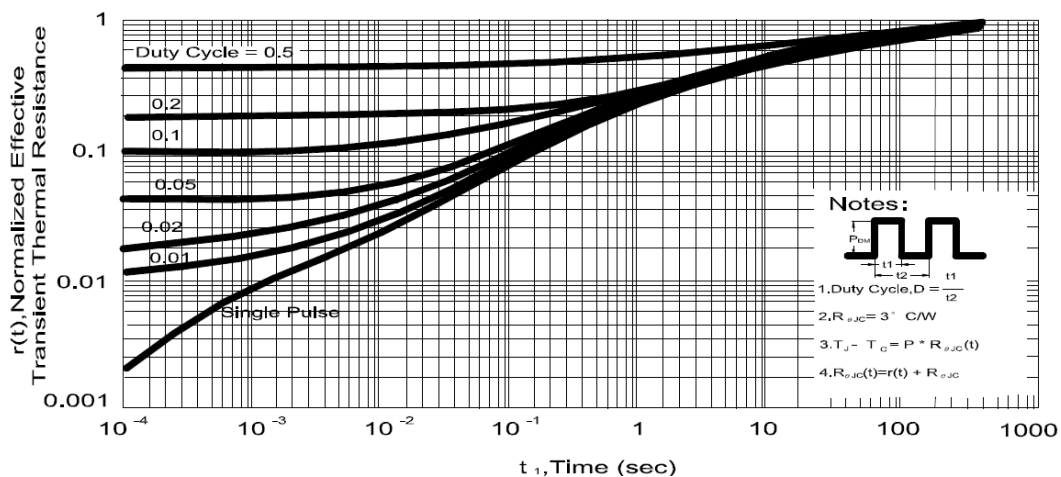
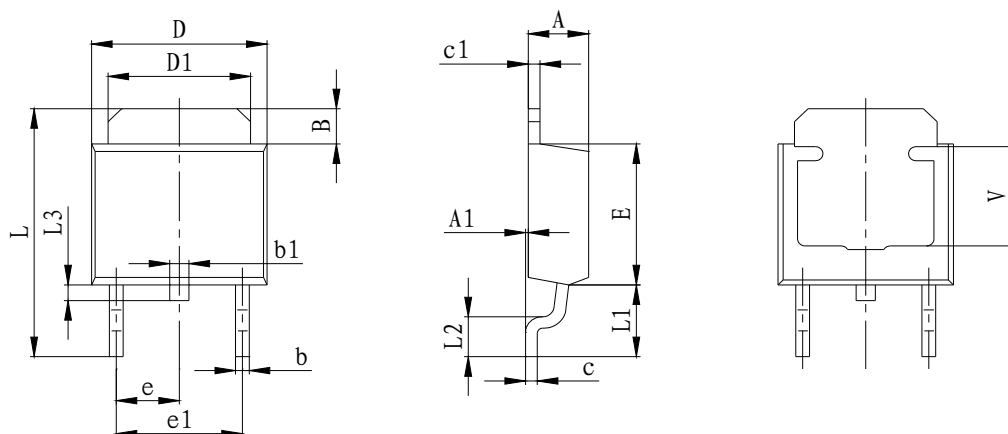


Figure 11: Transient Thermal Response Curve



PACKAGE MECHANICAL DATA

TO-252 Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF.		0.150 REF.	